Lattice Semiconductor Corporation - LFE2M35E-6F672C Datasheet

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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	4250
Number of Logic Elements/Cells	34000
Total RAM Bits	2151424
Number of I/O	410
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m35e-6f672c

Figure 2-1. Simplified Block Diagram, ECP2-6 Device (Top Level)

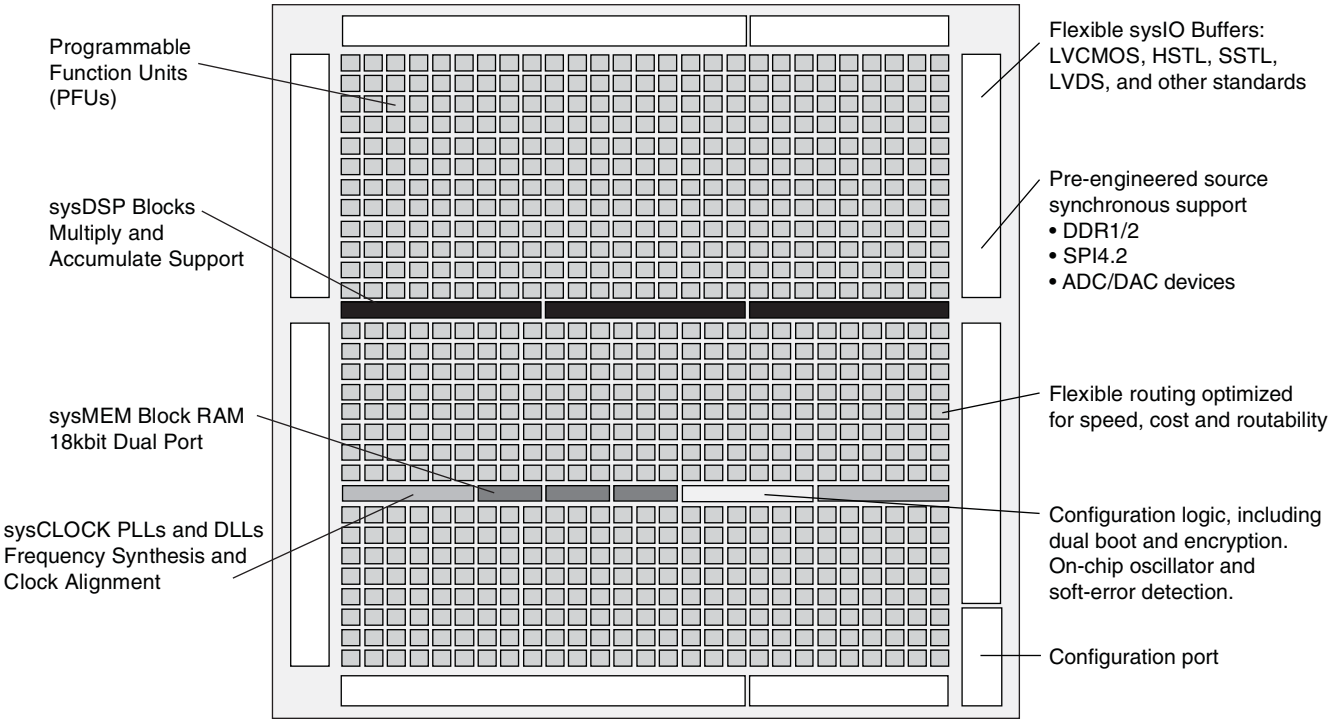

Figure 2-2. Simplified Block Diagram, ECP2M20 Device (Top Level)

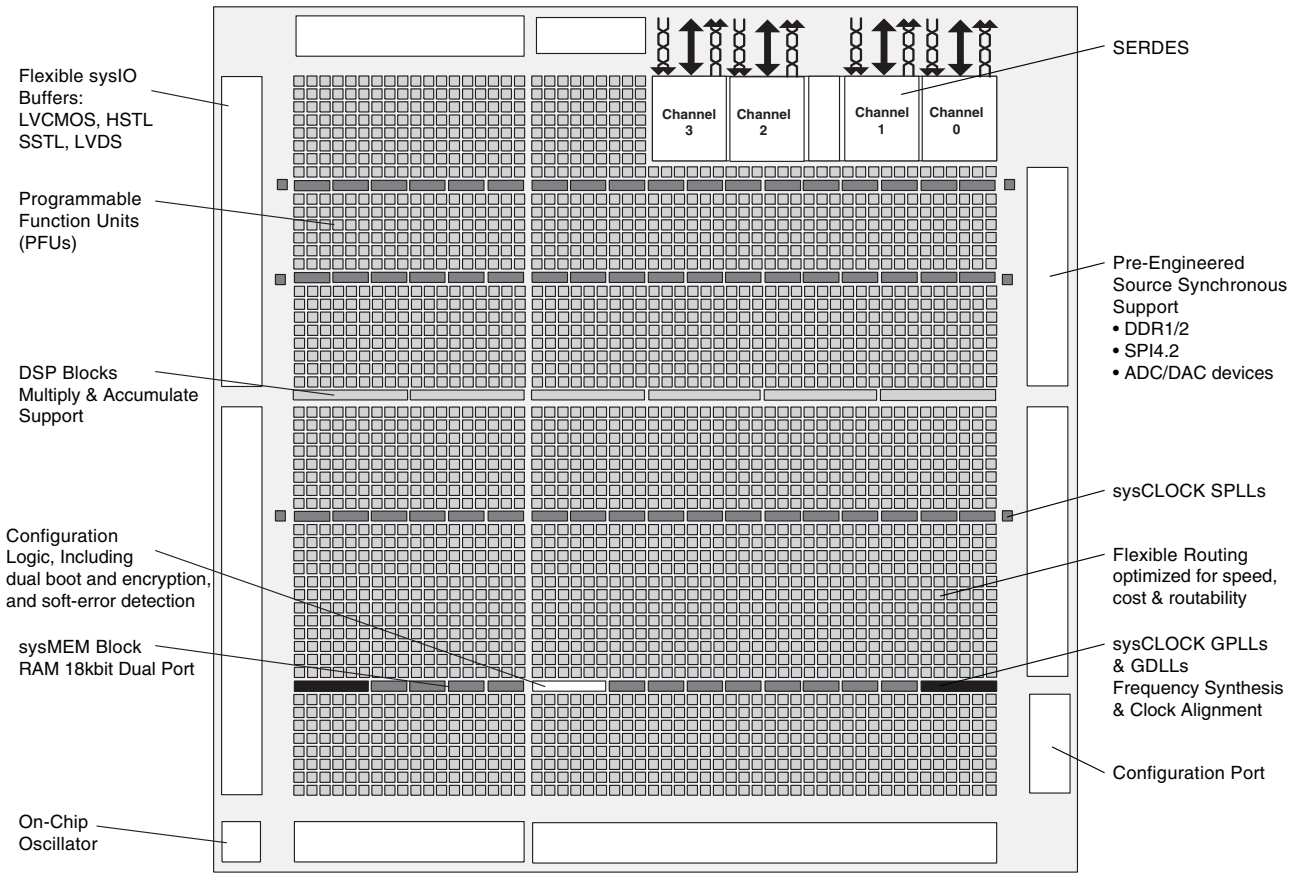

Table 2-12. PIO Signals List

Name	Type	Description
CE0, CE1	Control from the core	Clock enables for input and output block flip-flops
CLK0, CLK1	Control from the core	System clocks for input and output blocks
ECLK1, ECLK2	Control from the core	Fast edge clocks
LSR	Control from the core	Local Set/Reset
GSRN	Control from routing	Global Set/Reset (active low)
INCK[2]	Input to the core	Input to Primary Clock Network or PLL reference inputs
DQS	Input to PIO	DQS signal from logic (routing) to PIO
INDD	Input to the core	Unregistered data input to core
INFF	Input to the core	Registered input on positive edge of the clock (CLK0)
IPOS0, IPOS1	Input to the core	Double data rate registered inputs to the core
QPOS0[1], QPOS1[1]	Input to the core	Gearbox pipelined inputs to the core
QNEG0[1], QNEG1[1]	Input to the core	Gearbox pipelined inputs to the core
OPOS0, ONEG0, OPOS2, ONEG2	Output data from the core	Output signals from the core for SDR and DDR operation
OPOS1 ONEG1	Tristate control from the core	Signals to Tristate Register block for DDR operation
DEL[3:0]	Control from the core	Dynamic input delay control bits
TD	Tristate control from the core	Tristate signal from the core used in SDR operation
DDRCLKPOL	Control from clock polarity bus	Controls the polarity of the clock (CLK0) that feed the DDR input block
DQSXFER	Control from core	Controls signal to the Output block

1. Signals available on left/right/bottom only.
2. Selected I/O.

PIO

The PIO contains four blocks: an input register block, output register block, tristate register block and a control logic block. These blocks contain registers for operating in a variety of modes along with the necessary clock and selection logic.

Input Register Block

The input register blocks for PIOs in left, right and bottom edges contain delay elements and registers that can be used to condition high-speed interface signals, such as DDR memory interfaces and source synchronous interfaces, before they are passed to the device core. Figure 2-29 shows the diagram of the input register block for left, right and bottom edges. The input register block for the top edge contains one memory element to register the input signal as shown in Figure 2-30. The following description applies to the input register block for PIOs in the left, right and bottom edges of the device.

Input signals are fed from the sysI/O buffer to the input register block (as signal DI). If desired, the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and, in selected blocks, the input to the DQS delay block. If an input delay is desired, designers can select either a fixed delay or a dynamic delay DEL[3:0]. The delay, if selected, reduces input register hold time requirements when using a global clock.

The input block allows three modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In DDR Mode, two registers are used to sample the data on the positive and negative edges of the DQS signal, creating two data streams, D0 and D1. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

for checking soft errors (SED) in SRAM. SED can be run on a programmed device when the user logic is not active. If a soft error occurs, during user mode (normal operation) the device can be programmed to either reload from a known good boot image or generate an error signal.

For further information about Soft Error Detect (SED) support, please see the list of additional technical documentation at the end of this data sheet.

External Resistor

LatticeECP2/M devices require a single external, 10K ohm ±1% value between the XRES pin and ground. Device configuration will not be completed if this resistor is missing. There is no boundary scan register on the external resistor pad.

On-Chip Oscillator

Every LatticeECP2/M device has an internal CMOS oscillator which is used to derive a Master Clock for configuration. The oscillator and the Master Clock run continuously and are available to user logic after configuration is completed. The software default value of the Master Clock is 2.5MHz. Table 2-16 lists all the available Master Configuration Clock frequencies for normal non-encrypted mode and encrypted mode. When a different Master Clock is selected during the design process, the following sequence takes place:

1. Device powers up with a Master Clock frequency of 3.1MHz.
2. During configuration, users select a different master clock frequency.
3. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.
4. If the user does not select a master clock frequency, then the configuration bitstream defaults to the Master Clock frequency of 2.5MHz.

This internal CMOS oscillator is available to the user by routing it as an input clock to the clock tree. For further information about the use of this oscillator for configuration or user mode, please see the list of additional technical documentation at the end of this data sheet.

Table 2-16. Selectable Master Clock (CCLK) Frequencies During Configuration

Non-Encrypted Mode CCLK (MHz)			Encrypted Mode CCLK (MHz)
2.5[1]	13.0	45.0	2.5[1]
4.3	15.0	55.0	5.4
5.4	20.0	60.0	10.0
6.9	26.0	—	—
8.1	30.0	—	—
9.2	34.0	—	—
10.0	41.0	130.0	—

1. Software default frequency.

Density Shifting

The LatticeECP2/M family is designed to ensure that different density devices in the same family and in the same package have the same pinout. Furthermore, the architecture ensures a high success rate when performing design migration from lower density devices to higher density devices. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likelihood of success in each case. Design migration between LatticeECP2 and LatticeECP2M families is not possible. For specific requirements relating to sysCONFIG pins of the ECP2M50, M70 and M100, see the Logic Signal Connections tables.

sysI/O Recommended Operating Conditions

Standard	V_{CCIO}			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3[2]	3.135	3.3	3.465	—	—	—
LVCMOS 2.5[2]	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2[2]	1.14	1.2	1.26	—	—	—
LVTTL[2]	3.135	3.3	3.465	—	—	—
PCI	3.135	3.3	3.465	—	—	—
SSTL18[2] Class I, II	1.71	1.8	1.89	0.833	0.9	0.969
SSTL2[2] Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3[2] Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL[2] 15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL[2] 18 Class I, II	1.71	1.8	1.89	0.816	0.9	1.08
LVDS[2]	2.375	2.5	2.625	—	—	—
MLVDS25[1]	2.375	2.5	2.625	—	—	—
LVPECL33[1, 2]	3.135	3.3	3.465	—	—	—
BLVDS25[1, 2]	2.375	2.5	2.625	—	—	—
RSDS[1, 2]	2.375	2.5	2.625	—	—	—
SSTL18D_I[2], II[2]	1.71	1.8	1.89	—	—	—
SSTL25D_ I[2], II[2]	2.375	2.5	2.625	—	—	—
SSTL33D_ I[2], II[2]	3.135	3.3	3.465	—	—	—
HSTL15D_ I[2]	1.425	1.5	1.575	—	—	—
HSTL18D_ I[2], II[2]	1.71	1.8	1.89	—	—	—

1. Inputs on chip. Outputs are implemented with the addition of external resistors.
2. Input on this standard does not depend on the value of V_{CCIO}.

RSDS

The LatticeECP2/M devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Signaling)

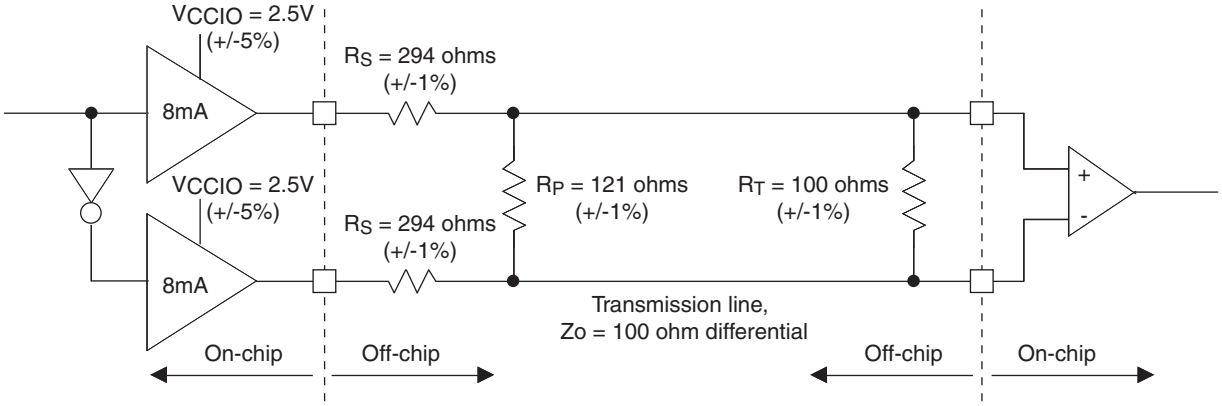

Table 3-5. RSDS DC Conditions[1]

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
V_{CCIO}	Output Driver Supply (+/-5%)	2.50	V
Z_{OUT}	Driver Impedance	20	Ω
R_S	Driver Series Resistor (+/-1%)	294	Ω
R_P	Driver Parallel Resistor (+/-1%)	121	Ω
R_T	Receiver Termination (+/-1%)	100	Ω
V_{OH}	Output High Voltage	1.35	V
V_{OL}	Output Low Voltage	1.15	V
V_{OD}	Output Differential Voltage	0.20	V
V_{CM}	Output Common Mode Voltage	1.25	V
Z_{BACK}	Back Impedance	101.5	Ω
I_{DC}	DC Output Current	3.66	mA

1. For input buffer, see LVDS table.

sysCLOCK SPLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)	Without external capacitor	33	—	420	MHz
		With external capacitor[5, 6]	2	—	420	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)	Without external capacitor	33	—	420	MHz
		With external capacitor[5]	5	—	50	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)	Without external capacitor	0.258	—	210	MHz
		With external capacitor[5]	0.039	—	25	MHz
f_{VCO}	PLL VCO Frequency		640	—	1280	MHz
f_{PFD}	Phase Detector Input Frequency	Without external capacitor	33	—	420	MHz
		With external capacitor[6]	2	—	50	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default Duty Cycle Selected[3]	45	50	55	%
t_{PH}[4]	Output Phase Accuracy		—	—	±0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	—	±125	ps
		$50 \leq f_{OUT} < 100$ MHz	—	—	0.025	UIPP
		$f_{OUT} < 50$ MHz	—	—	0.04	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider Ratio = Integer	—	—	±250	ps
t_W	Output Clock Pulse Width	At 90% or 10%	1	—	—	ns
t_{LOCK}[2]	PLL Lock-in Time	Without external capacitor	—	—	150	µs
		With external capacitor[5]	—	—	500	µs
t_{IPJIT}	Input Clock Period Jitter		—	—	±200	ps
t_{FBKDLY}	External Feedback Delay		—	—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t_{RST}	RST Pulse Width (RSTK)		15	—	—	ns
	Reset Signal Pulse Width (RST)	Without external capacitor	500	—	—	ns
		With external capacitor[5]	20	—	—	µs

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock and no additional I/O pins toggling.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. Phase accuracy of CLKOS compared to CLKOP.
5. Value of external capacitor: 5.6 nF ±20%, NPO dielectric, ceramic chip capacitor, 1206 or smaller package, connected to PLLCAP pin.
6. f_{OUT} (max) = f_{IN} * 10 for f_{IN} < 5MHz.

LatticeECP2/M sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Byte Data Flow				
t_{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7	—	ns
t_{HCBDI}	Byte D[0:7] Hold Time to CCLK	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
t_{SUCS}	CSN[0:1] Setup Time to CCLK	7	—	ns
t_{HCS}	CSN[0:1] Hold Time to CCLK	1	—	ns
t_{SUWD}	Write Signal Setup Time to CCLK	7	—	ns
t_{HWD}	Write Signal Hold Time to CCLK	1	—	ns
t_{DCB}	CCLK to BUSY Delay Time	—	12	ns
t_{CORD}	CCLK to Out for Read Data	—	12	ns
sysCONFIG Byte Slave Clocking				
t_{BSCH}	Byte Slave CCLK Minimum High Pulse	6	—	ns
t_{BSCL}	Byte Slave CCLK Minimum Low Pulse	9	—	ns
t_{BSCYC}	Byte Slave CCLK Cycle Time	15	—	ns
sysCONFIG Serial (Bit) Data Flow				
t_{SUSCDI}	DI Setup Time to CCLK Slave Mode	7	—	ns
t_{HSCDI}	DI Hold Time to CCLK Slave Mode	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
sysCONFIG Serial Slave Clocking				
t_{SSCH}	Serial Slave CCLK Minimum High Pulse	6	—	ns
t_{SSCL}	Serial Slave CCLK Minimum Low Pulse	6	—	ns
sysCONFIG POR, Initialization and Wake-up				
t_{ICFG}	Minimum Vcc to INITN High	—	28	ms
t_{VMC}	Time from t_{ICFG} to Valid Master CCLK	—	2	us
t_{PRGMRJ}	PROGRAMN Pin Pulse Rejection	—	8	ns
t_{PRGM}	PROGRAMN Low Time to Start Configuration	25	—	ns
t_{DINIT}	PROGRAMN High to INITN High Delay[1]	—	1.5	ms
$t_{DPPINIT}$	Delay Time from PROGRAMN Low to INITN Low	—	37	ns
$t_{DPPDONE}$	Delay Time from PROGRAMN Low to DONE Low	—	37	ns
t_{IODISS}	User I/O Disable from PROGRAMN Low	—	35	ns
t_{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake-up Sequence	—	25	ns
t_{MWC}	Additional Wake Master Clock Signals after DONE Pin High	120	—	cycles
sysCONFIG SPI Port[2]				
t_{CFGX}	INITN High to CCLK Low	—	1	µs
t_{CSSPI}	INITN High to CSSPIN Low	—	2	us
t_{CSCCLK}	CCLK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CCLK Low to Output Valid	—	15	ns
t_{SOE}	CSSPIN[0:1] Active Setup Time	300	—	ns
t_{CSPID}	CSSPIN[0:1] Low to First CCLK Edge Setup Time	300+3cyc	600+6cyc	ns

Available Device Resources by Package, LatticeECP2

Resource	Device	256 fpBGA	484 fpBGA	672 fpBGA	900 fpBGA
PLL/DLL	ECP2-6	4	—	—	—
	ECP2-12	4	4	—	—
	ECP2-20	4	4	4	—
	ECP2-35	—	4	4	—
	ECP2-50	—	6	6	—
	ECP2-70	—	—	8	8

Available Device Resources by Package, LatticeECP2M

Resource	Device	256 fpBGA	484 fpBGA	672 fpBGA	900 fpBGA	1152 fpBGA
PLL/DLL	ECP2M20	10	10	—	—	—
	ECP2M35	10	10	10	—	—
	ECP2M50	—	10	10	10	—
	ECP2M70	—	—	—	10	10
	ECP2M100	—	—	—	10	10

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GND	GNDIO2	-			GNDIO2	-		
L21	PR18B	2	RDQ16	C (LVDS)*	PR24B	2	RDQ22	C (LVDS)*
K22	PR18A	2	RDQ16	T (LVDS)*	PR24A	2	RDQ22	T (LVDS)*
M24	PR17B	2	RDQ16	C	PR23B	2	RDQ22	C
N23	PR17A	2	RDQ16	T	PR23A	2	RDQ22	T
VCCIO	VCCIO2	2			VCCIO2	2		
K26	PR16B	2	RDQ16	C (LVDS)*	PR22B	2	RDQ22	C (LVDS)*
K25	PR16A	2	RDQS16	T (LVDS)*	PR22A	2	RDQS22	T (LVDS)*
M20	PR15B	2	RDQ16	C	PR21B	2	RDQ22	C
GND	GNDIO2	-			GNDIO2	-		
M19	PR15A	2	RDQ16	T	PR21A	2	RDQ22	T
L22	PR14B	2	RDQ16	C (LVDS)*	PR20B	2	RDQ22	C (LVDS)*
M22	PR14A	2	RDQ16	T (LVDS)*	PR20A	2	RDQ22	T (LVDS)*
K21	PR13B	2	RDQ16	C	PR19B	2	RDQ22	C
VCCIO	VCCIO2	2			VCCIO2	2		
M21	PR13A	2	RDQ16	T	PR19A	2	RDQ22	T
K24	PR12B	2	RDQ16	C (LVDS)*	PR18B	2	RDQ22	C (LVDS)*
J24	PR12A	2	RDQ16	T (LVDS)*	PR18A	2	RDQ22	T (LVDS)*
GND	GNDIO2	-			GNDIO2	-		
VCCIO	VCCIO2	2			VCCIO2	2		
L20	VCC	-			NC	-		
GND	GNDIO2	-			GNDIO2	-		
J26	NC	-			NC	-		
J25	NC	-			NC	-		
J23	NC	-			NC	-		
K23	NC	-			NC	-		
VCCIO	VCCIO2	2			VCCIO2	2		
H26	NC	-			NC	-		
H25	NC	-			NC	-		
H24	NC	-			NC	-		
GND	GNDIO2	-			GNDIO2	-		
H23	NC	-			NC	-		
VCCIO	VCCIO2	2			VCCIO2	2		
G26	PR11B	2	RDQ8	C	PR17B	2	RDQ14	C
GND	GNDIO2	-			GNDIO2	-		
G25	PR11A	2	RDQ8	T	PR17A	2	RDQ14	T
F26	PR10B	2	RDQ8	C (LVDS)*	PR16B	2	RDQ14	C (LVDS)*
F25	PR10A	2	RDQ8	T (LVDS)*	PR16A	2	RDQ14	T (LVDS)*
K20	PR9B	2	RDQ8	C	PR15B	2	RDQ14	C
VCCIO	VCCIO2	2			VCCIO2	2		
L19	PR9A	2	RDQ8	T	PR15A	2	RDQ14	T
E26	PR8B	2	RDQ8	C (LVDS)*	PR14B	2	RDQ14	C (LVDS)*
E25	PR8A	2	RDQS8	T (LVDS)*	PR14A	2	RDQS14	T (LVDS)*
GND	GNDIO2	-			GNDIO2	-		
J22	PR7B	2	RDQ8	C	PR13B	2	RDQ14	C
H22	PR7A	2	RDQ8	T	PR13A	2	RDQ14	T

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
L23	VCCIO2	2			VCCIO2	2		
M17	VCCIO2	2			VCCIO2	2		
M18	VCCIO2	2			VCCIO2	2		
AA23	VCCIO3	3			VCCIO3	3		
R17	VCCIO3	3			VCCIO3	3		
R18	VCCIO3	3			VCCIO3	3		
T23	VCCIO3	3			VCCIO3	3		
V20	VCCIO3	3			VCCIO3	3		
AC16	VCCIO4	4			VCCIO4	4		
AC21	VCCIO4	4			VCCIO4	4		
U15	VCCIO4	4			VCCIO4	4		
V15	VCCIO4	4			VCCIO4	4		
Y18	VCCIO4	4			VCCIO4	4		
AC11	VCCIO5	5			VCCIO5	5		
AC6	VCCIO5	5			VCCIO5	5		
U12	VCCIO5	5			VCCIO5	5		
V12	VCCIO5	5			VCCIO5	5		
Y9	VCCIO5	5			VCCIO5	5		
AA4	VCCIO6	6			VCCIO6	6		
R10	VCCIO6	6			VCCIO6	6		
R9	VCCIO6	6			VCCIO6	6		
T4	VCCIO6	6			VCCIO6	6		
V7	VCCIO6	6			VCCIO6	6		
F4	VCCIO7	7			VCCIO7	7		
J7	VCCIO7	7			VCCIO7	7		
L4	VCCIO7	7			VCCIO7	7		
M10	VCCIO7	7			VCCIO7	7		
M9	VCCIO7	7			VCCIO7	7		
AE25	VCCIO8	8			VCCIO8	8		
V18	VCCIO8	8			VCCIO8	8		
J10	VCCAUX	-			VCCAUX	-		
J11	VCCAUX	-			VCCAUX	-		
J16	VCCAUX	-			VCCAUX	-		
J17	VCCAUX	-			VCCAUX	-		
K18	VCCAUX	-			VCCAUX	-		
K9	VCCAUX	-			VCCAUX	-		
L18	VCCAUX	-			VCCAUX	-		
L9	VCCAUX	-			VCCAUX	-		
T18	VCCAUX	-			VCCAUX	-		
T9	VCCAUX	-			VCCAUX	-		
U18	VCCAUX	-			VCCAUX	-		
U9	VCCAUX	-			VCCAUX	-		
V10	VCCAUX	-			VCCAUX	-		
V11	VCCAUX	-			VCCAUX	-		
V16	VCCAUX	-			VCCAUX	-		
V17	VCCAUX	-			VCCAUX	-		

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
W5	PL71B	6	LDQ75	C (LVDS)*	PL84B	6	LDQ88	C (LVDS)*
AC1	PL72A	6	LDQ75	T	PL85A	6	LDQ88	T
AD1	PL72B	6	LDQ75	C	PL85B	6	LDQ88	C
VCCIO	VCCIO6	6			VCCIO6	6		
Y6	PL73A	6	LDQ75	T (LVDS)*	PL86A	6	LDQ88	T (LVDS)*
Y5	PL73B	6	LDQ75	C (LVDS)*	PL86B	6	LDQ88	C (LVDS)*
AE2	PL74A	6	LDQ75	T	PL87A	6	LDQ88	T
AD2	PL74B	6	LDQ75	C	PL87B	6	LDQ88	C
GND	GNDIO6	-			GNDIO6	-		
AB3	PL75A	6	LDQS75	T (LVDS)*	PL88A	6	LDQS88	T (LVDS)*
AB2	PL75B	6	LDQ75	C (LVDS)*	PL88B	6	LDQ88	C (LVDS)*
W7	PL76A	6	LDQ75	T	PL89A	6	LDQ88	T
VCCIO	VCCIO6	6			VCCIO6	6		
W8	PL76B	6	LDQ75	C	PL89B	6	LDQ88	C
Y7	PL77A	6	LDQ75	T (LVDS)*	PL90A	6	LDQ88	T (LVDS)*
Y8	PL77B	6	LDQ75	C (LVDS)*	PL90B	6	LDQ88	C (LVDS)*
AC2	PL78A	6	LDQ75	T	PL91A	6	LDQ88	T
GND	GNDIO6	-			GNDIO6	-		
AD3	PL78B	6	LDQ75	C	PL91B	6	LDQ88	C
AC3	TCK	-			TCK	-		
AA8	TDI	-			TDI	-		
AB4	TMS	-			TMS	-		
AA5	TDO	-			TDO	-		
AB5	VCCJ	-			VCCJ	-		
AE3	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T
AF3	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C
AC4	PB3A	5	BDQ6	T	PB3A	5	BDQ6	T
AD4	PB3B	5	BDQ6	C	PB3B	5	BDQ6	C
AE4	PB4A	5	BDQ6	T	PB4A	5	BDQ6	T
AF4	PB4B	5	BDQ6	C	PB4B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
V9	PB5A	5	BDQ6	T	PB5A	5	BDQ6	T
W9	PB5B	5	BDQ6	C	PB5B	5	BDQ6	C
GND	GNDIO5	-			GNDIO5	-		
AA6	PB6A	5	BDQS6	T	PB6A	5	BDQS6	T
AB6	PB6B	5	BDQ6	C	PB6B	5	BDQ6	C
AC5	PB7A	5	BDQ6	T	PB7A	5	BDQ6	T
AD5	PB7B	5	BDQ6	C	PB7B	5	BDQ6	C
AA7	PB8A	5	BDQ6	T	PB8A	5	BDQ6	T
AB7	PB8B	5	BDQ6	C	PB8B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
AE5	PB9A	5	BDQ6	T	PB9A	5	BDQ6	T
AF5	PB9B	5	BDQ6	C	PB9B	5	BDQ6	C
AC7	PB10A	5	BDQ6	T	PB10A	5	BDQ6	T
AD7	PB10B	5	BDQ6	C	PB10B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ6	PB16A	5	BDQ15	T
AK6	PB16B	5	BDQ15	C
VCCIO	VCCIO5	5		
GND	GNDIO5	-		
AD10	PB29A	5	BDQ33	T
AF10	PB29B	5	BDQ33	C
AC11	PB30A	5	BDQ33	T
AD11	PB30B	5	BDQ33	C
AG9	PB31A	5	BDQ33	T
AH9	PB31B	5	BDQ33	C
VCCIO	VCCIO5	99		
AE11	PB32A	5	BDQ33	T
AG10	PB32B	5	BDQ33	C
GND	GNDIO5	-		
AJ9	PB33A	5	BDQS33	T
AK9	PB33B	5	BDQ33	C
AF11	PB34A	5	BDQ33	T
AH10	PB34B	5	BDQ33	C
AC12	PB35A	5	BDQ33	T
AE12	PB35B	5	BDQ33	C
VCCIO	VCCIO5	5		
AD12	PB36A	5	BDQ33	T
AF12	PB36B	5	BDQ33	C
AJ10	PB37A	5	BDQ33	T
AK10	PB37B	5	BDQ33	C
GND	GNDIO5	-		
AG11	PB38A	5	BDQ42	T
AH11	PB38B	5	BDQ42	C
AE13	PB39A	5	BDQ42	T
AC13	PB39B	5	BDQ42	C
AF13	PB40A	5	BDQ42	T
VCCIO	VCCIO5	5		
AD13	PB40B	5	BDQ42	C
AJ11	PB41A	5	BDQ42	T
AK11	PB41B	5	BDQ42	C
AD14	PB42A	5	BDQS42	T
GND	GNDIO5	-		
AC14	PB42B	5	BDQ42	C
AG12	PB43A	5	BDQ42	T
AE14	PB43B	5	BDQ42	C
AJ12	PB44A	5	BDQ42	T
VCCIO	VCCIO5	5		
AK12	PB44B	5	BDQ42	C

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U12	PB59B	4	BDQ60	C
GNDIO	GNDIO4	-		
AA12	PB60A	4	BDQS60	T
Y12	PB60B	4	BDQ60	C
V12	PB61A	4	BDQ60	T
W12	PB61B	4	BDQ60	C
AB12	PB62A	4	BDQ60	T
AA13	PB62B	4	BDQ60	C
VCCIO	VCCIO4	4		
T12	PB63A	4	BDQ60	T
U13	PB63B	4	BDQ60	C
V13	PB64A	4	BDQ60	T
T13	PB64B	4	BDQ60	C
GNDIO	GNDIO4	-		
AB13	PB65A	4	BDQ69	T
AB14	PB65B	4	BDQ69	C
U14	PB66A	4	BDQ69	T
T14	PB66B	4	BDQ69	C
AA14	PB67A	4	BDQ69	T
VCCIO	VCCIO4	4		
Y14	PB67B	4	BDQ69	C
W14	PB68A	4	BDQ69	T
V14	PB68B	4	BDQ69	C
AB15	PB69A	4	BDQS69	T
GNDIO	GNDIO4	-		
AA15	PB69B	4	BDQ69	C
V15	PB70A	4	BDQ69	T
U15	PB70B	4	BDQ69	C
AB16	PB71A	4	BDQ69	T
VCCIO	VCCIO4	4		
AA16	PB71B	4	BDQ69	C
AB17	PB72A	4	BDQ69	T
AA17	PB72B	4	BDQ69	C
GNDIO	GNDIO4	-		
W20	CFG2	8		
V20	CFG1	8		
V19	CFG0	8		
V22	PROGRAMN	8		
W22	CCLK	8		
U18	INITN	8		
U22	DONE	8		
GNDIO	GNDIO8	-		
U20	WRITEN***	8		

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C6	PT12B	0		C	PT12B	0		C
F10	PT12A	0		T	PT12A	0		T
D7	PT11B	0		C	PT11B	0		C
H11	PT11A	0		T	PT11A	0		T
D5	PT10B	0		C	PT10B	0		C
GNDIO	GNDIO0	-			GNDIO0	-		
E6	PT10A	0		T	PT10A	0		T
G10	PT9B	0		C	PT9B	0		C
F9	PT9A	0		T	PT9A	0		T
H10	PT8B	0		C	PT8B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
E7	PT8A	0		T	PT8A	0		T
B3	PT7B	0		C	PT7B	0		C
C5	PT7A	0		T	PT7A	0		T
B2	PT6B	0		C	PT6B	0		C
C4	PT6A	0		T	PT6A	0		T
G9	PT5B	0		C	PT5B	0		C
GNDIO	GNDIO0	-			GNDIO0	-		
F7	PT5A	0		T	PT5A	0		T
C3	PT4B	0		C	PT4B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
D4	PT4A	0		T	PT4A	0		T
J10	PT3B	0		C	PT3B	0		C
F8	PT3A	0		T	PT3A	0		T
G8	PT2B	0		C	PT2B	0		C
G7	PT2A	0		T	PT2A	0		T
L12	VCC	-			VCC	-		
L13	VCC	-			VCC	-		
L14	VCC	-			VCC	-		
L15	VCC	-			VCC	-		
M11	VCC	-			VCC	-		
M12	VCC	-			VCC	-		
M15	VCC	-			VCC	-		
M16	VCC	-			VCC	-		
N11	VCC	-			VCC	-		
N16	VCC	-			VCC	-		
P11	VCC	-			VCC	-		
P16	VCC	-			VCC	-		
R11	VCC	-			VCC	-		
R12	VCC	-			VCC	-		
R15	VCC	-			VCC	-		
R16	VCC	-			VCC	-		
T12	VCC	-			VCC	-		
T13	VCC	-			VCC	-		
T14	VCC	-			VCC	-		
T15	VCC	-			VCC	-		
B12	VCCIO0	0			VCCIO0	0		
B7	VCCIO0	0			VCCIO0	0		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ30	LRC_SQ_VCCIB0	13		
AK29	LRC_SQ_HDINP0	13		T
AH30	LRC_SQ_VCCRX0	13		
AG27	CFG2	8		
AD25	CFG1	8		
AG28	CFG0	8		
AG30	PROGRAMN	8		
AG29	CCLK	8		
AC24	INITN	8		
AF27	DONE	8		
GNDIO	GNDIO8	-		
AF28	WRITEN***	8		
AE26	CS1N***	8		
AB23	CSN***	8		
AF29	D0/SPIFASTN***	8		
VCCIO	VCCIO8	8		
AF30	D1***	8		
AD26	D2***	8		
AE29	D3***	8		
GNDIO	GNDIO8	-		
AE30	D4***	8		
AD29	D5***	8		
AC25	D6***	8		
AD30	D7/SPID0***	8		
VCCIO	VCCIO8	8		
AA22	DI/CSSPI0N***	8		
AC26	DOUT/CSON/CSSPI1N***	8		
AA23	BUSY/SISPI***	8		
AB22	RLM0_PLLCAP	3		
AC27	PR102B	3	RLM0_GDLLC_FB_A/RDQ99	C
GNDIO	GNDIO3	-		
AC28	PR102A	3	RLM0_GDLLT_FB_A/RDQ99	T
AC29	PR101B	3	RLM0_GDLLC_IN_A**/RDQ99	C (LVDS)*
AC30	PR101A	3	RLM0_GDLLT_IN_A**/RDQ99	T (LVDS)*
AB30	PR100B	3	RLM0_GPLLC_IN_A**/RDQ99	C
VCCIO	VCCIO3	3		
AA30	PR100A	3	RLM0_GPLLT_IN_A**/RDQ99	T
AB29	PR99B	3	RLM0_GPLLC_FB_A/RDQ99	C (LVDS)*
AB28	PR99A	3	RLM0_GPLLT_FB_A/RDQS99	T (LVDS)*
GNDIO	GNDIO3	-		
Y22	PR98B	3	RDQ99	C
Y23	PR98A	3	RDQ99	T
AB26	PR97B	3	RDQ99	C (LVDS)*

LatticeECP2 Standard Series Devices, Lead-Free Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6E-5TN144C	90	1.2V	-5	Lead-Free TQFP	144	COM	6
LFE2-6E-6TN144C	90	1.2V	-6	Lead-Free TQFP	144	COM	6
LFE2-6E-7TN144C	90	1.2V	-7	Lead-Free TQFP	144	COM	6
LFE2-6E-5FN256C	190	1.2V	-5	Lead-Free fpBGA	256	COM	6
LFE2-6E-6FN256C	190	1.2V	-6	Lead-Free fpBGA	256	COM	6
LFE2-6E-7FN256C	190	1.2V	-7	Lead-Free fpBGA	256	COM	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12E-5TN144C	93	1.2V	-5	Lead-Free TQFP	144	COM	12
LFE2-12E-6TN144C	93	1.2V	-6	Lead-Free TQFP	144	COM	12
LFE2-12E-7TN144C	93	1.2V	-7	Lead-Free TQFP	144	COM	12
LFE2-12E-5QN208C	131	1.2V	-5	Lead-Free PQFP	208	COM	12
LFE2-12E-6QN208C	131	1.2V	-6	Lead-Free PQFP	208	COM	12
LFE2-12E-7QN208C	131	1.2V	-7	Lead-Free PQFP	208	COM	12
LFE2-12E-5FN256C	193	1.2V	-5	Lead-Free fpBGA	256	COM	12
LFE2-12E-6FN256C	193	1.2V	-6	Lead-Free fpBGA	256	COM	12
LFE2-12E-7FN256C	193	1.2V	-7	Lead-Free fpBGA	256	COM	12
LFE2-12E-5FN484C	297	1.2V	-5	Lead-Free fpBGA	484	COM	12
LFE2-12E-6FN484C	297	1.2V	-6	Lead-Free fpBGA	484	COM	12
LFE2-12E-7FN484C	297	1.2V	-7	Lead-Free fpBGA	484	COM	12

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-20E-5QN208C	131	1.2V	-5	Lead-Free PQFP	208	COM	20
LFE2-20E-6QN208C	131	1.2V	-6	Lead-Free PQFP	208	COM	20
LFE2-20E-7QN208C	131	1.2V	-7	Lead-Free PQFP	208	COM	20
LFE2-20E-5FN256C	193	1.2V	-5	Lead-Free fpBGA	256	COM	20
LFE2-20E-6FN256C	193	1.2V	-6	Lead-Free fpBGA	256	COM	20
LFE2-20E-7FN256C	193	1.2V	-7	Lead-Free fpBGA	256	COM	20
LFE2-20E-5FN484C	331	1.2V	-5	Lead-Free fpBGA	484	COM	20
LFE2-20E-6FN484C	331	1.2V	-6	Lead-Free fpBGA	484	COM	20
LFE2-20E-7FN484C	331	1.2V	-7	Lead-Free fpBGA	484	COM	20
LFE2-20E-5FN672C	402	1.2V	-5	Lead-Free fpBGA	672	COM	20
LFE2-20E-6FN672C	402	1.2V	-6	Lead-Free fpBGA	672	COM	20
LFE2-20E-7FN672C	402	1.2V	-7	Lead-Free fpBGA	672	COM	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100E-5FN1152C	520	1.2V	-5	Lead-Free fpBGA	1152	COM	100
LFE2M100E-6FN1152C	520	1.2V	-6	Lead-Free fpBGA	1152	COM	100
LFE2M100E-7FN1152C	520	1.2V	-7	Lead-Free fpBGA	1152	COM	100
LFE2M100E-5FN900C	416	1.2V	-5	Lead-Free fpBGA	900	COM	100
LFE2M100E-6FN900C	416	1.2V	-6	Lead-Free fpBGA	900	COM	100
LFE2M100E-7FN900C	416	1.2V	-7	Lead-Free fpBGA	900	COM	100

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20E-5FN484I	304	1.2V	-5	Lead-Free fpBGA	484	IND	20
LFE2M20E-6FN484I	304	1.2V	-6	Lead-Free fpBGA	484	IND	20
LFE2M20E-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	IND	20
LFE2M20E-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	IND	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35E-5FN672I	410	1.2V	-5	Lead-Free fpBGA	672	IND	35
LFE2M35E-6FN672I	410	1.2V	-6	Lead-Free fpBGA	672	IND	35
LFE2M35E-5FN484I	303	1.2V	-5	Lead-Free fpBGA	484	IND	35
LFE2M35E-6FN484I	303	1.2V	-6	Lead-Free fpBGA	484	IND	35
LFE2M35E-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	IND	35
LFE2M35E-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	IND	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50E-5FN900I	410	1.2V	-5	Lead-Free fpBGA	900	Ind	50
LFE2M50E-6FN900I	410	1.2V	-6	Lead-Free fpBGA	900	Ind	50
LFE2M50E-5FN672I	372	1.2V	-5	Lead-Free fpBGA	672	Ind	50
LFE2M50E-6FN672I	372	1.2V	-6	Lead-Free fpBGA	672	Ind	50
LFE2M50E-5FN484I	270	1.2V	-5	Lead-Free fpBGA	484	Ind	50
LFE2M50E-6FN484I	270	1.2V	-6	Lead-Free fpBGA	484	Ind	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70E-5FN1152I	436	1.2V	-5	Lead-Free fpBGA	1152	Ind	70
LFE2M70E-6FN1152I	436	1.2V	-6	Lead-Free fpBGA	1152	Ind	70
LFE2M70E-5FN900I	416	1.2V	-5	Lead-Free fpBGA	900	Ind	70
LFE2M70E-6FN900I	416	1.2V	-6	Lead-Free fpBGA	900	Ind	70

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20SE-5F484I	304	1.2V	-5	fpBGA	484	Ind	20
LFE2M20SE-6F484I	304	1.2V	-6	fpBGA	484	Ind	20
LFE2M20SE-5F256I	140	1.2V	-5	fpBGA	256	Ind	20
LFE2M20SE-6F256I	140	1.2V	-6	fpBGA	256	Ind	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35SE-5F672I	410	1.2V	-5	fpBGA	672	Ind	35
LFE2M35SE-6F672I	410	1.2V	-6	fpBGA	672	Ind	35
LFE2M35SE-5F484I	303	1.2V	-5	fpBGA	484	Ind	35
LFE2M35SE-6F484I	303	1.2V	-6	fpBGA	484	Ind	35
LFE2M35SE-5F256I	140	1.2V	-5	fpBGA	256	Ind	35
LFE2M35SE-6F256I	140	1.2V	-6	fpBGA	256	Ind	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50SE-5F900I	410	1.2V	-5	fpBGA	900	Ind	50
LFE2M50SE-6F900I	410	1.2V	-6	fpBGA	900	Ind	50
LFE2M50SE-5F672I	372	1.2V	-5	fpBGA	672	Ind	50
LFE2M50SE-6F672I	372	1.2V	-6	fpBGA	672	Ind	50
LFE2M50SE-5F484I	270	1.2V	-5	fpBGA	484	Ind	50
LFE2M50SE-6F484I	270	1.2V	-6	fpBGA	484	Ind	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70SE-5F1152I	436	1.2V	-5	fpBGA	1152	Ind	70
LFE2M70SE-6F1152I	436	1.2V	-6	fpBGA	1152	Ind	70
LFE2M70SE-5F900I	416	1.2V	-5	fpBGA	900	Ind	70
LFE2M70SE-6F900I	416	1.2V	-6	fpBGA	900	Ind	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100SE-5F1152I	520	1.2V	-5	fpBGA	1152	Ind	100
LFE2M100SE-6F1152I	520	1.2V	-6	fpBGA	1152	Ind	100
LFE2M100SE-5F900I	416	1.2V	-5	fpBGA	900	Ind	100
LFE2M100SE-6F900I	416	1.2V	-6	fpBGA	900	Ind	100

LatticeECP2M S-Series Devices, Lead-Free Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20SE-5FN484C	304	1.2V	-5	Lead-Free fpBGA	484	Com	20
LFE2M20SE-6FN484C	304	1.2V	-6	Lead-Free fpBGA	484	Com	20
LFE2M20SE-7FN484C	304	1.2V	-7	Lead-Free fpBGA	484	Com	20
LFE2M20SE-5FN256C	140	1.2V	-5	Lead-Free fpBGA	256	Com	20
LFE2M20SE-6FN256C	140	1.2V	-6	Lead-Free fpBGA	256	Com	20
LFE2M20SE-7FN256C	140	1.2V	-7	Lead-Free fpBGA	256	Com	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35SE-5FN672C	410	1.2V	-5	Lead-Free fpBGA	672	Com	35
LFE2M35SE-6FN672C	410	1.2V	-6	Lead-Free fpBGA	672	Com	35
LFE2M35SE-7FN672C	410	1.2V	-7	Lead-Free fpBGA	672	Com	35
LFE2M35SE-5FN484C	303	1.2V	-5	Lead-Free fpBGA	484	Com	35
LFE2M35SE-6FN484C	303	1.2V	-6	Lead-Free fpBGA	484	Com	35
LFE2M35SE-7FN484C	303	1.2V	-7	Lead-Free fpBGA	484	Com	35
LFE2M35SE-5FN256C	140	1.2V	-5	Lead-Free fpBGA	256	Com	35
LFE2M35SE-6FN256C	140	1.2V	-6	Lead-Free fpBGA	256	Com	35
LFE2M35SE-7FN256C	140	1.2V	-7	Lead-Free fpBGA	256	Com	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50SE-5FN900C	410	1.2V	-5	Lead-Free fpBGA	900	Com	50
LFE2M50SE-6FN900C	410	1.2V	-6	Lead-Free fpBGA	900	Com	50
LFE2M50SE-7FN900C	410	1.2V	-7	Lead-Free fpBGA	900	Com	50
LFE2M50SE-5FN672C	372	1.2V	-5	Lead-Free fpBGA	672	Com	50
LFE2M50SE-6FN672C	372	1.2V	-6	Lead-Free fpBGA	672	Com	50
LFE2M50SE-7FN672C	372	1.2V	-7	Lead-Free fpBGA	672	Com	50
LFE2M50SE-5FN484C	270	1.2V	-5	Lead-Free fpBGA	484	Com	50
LFE2M50SE-6FN484C	270	1.2V	-6	Lead-Free fpBGA	484	Com	50
LFE2M50SE-7FN484C	270	1.2V	-7	Lead-Free fpBGA	484	Com	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70SE-5FN1152C	436	1.2V	-5	Lead-Free fpBGA	1152	Com	70
LFE2M70SE-6FN1152C	436	1.2V	-6	Lead-Free fpBGA	1152	Com	70
LFE2M70SE-7FN1152C	436	1.2V	-7	Lead-Free fpBGA	1152	Com	70
LFE2M70SE-5FN900C	416	1.2V	-5	Lead-Free fpBGA	900	Com	70
LFE2M70SE-6FN900C	416	416	-6	Lead-Free fpBGA	900	Com	70
LFE2M70SE-7FN900C	416	416	-7	Lead-Free fpBGA	900	Com	70

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVCMOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
			Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
April 2008	03.1	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
June 2008	03.2	Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Clarification of the operation of the secondary clock regions.
		DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
August 2008	03.3	Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPIm Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t_{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.